

High Speed Electronics 2019 – Exercise 2 Solutions

1. a) Charge centroid capacitance accounts for the band bending. Hence the total gate capacitance is

$$\frac{1}{C_g} = \frac{1}{C_{ox}} + \frac{1}{C_q} + \frac{1}{C_c}$$

$$\frac{1}{C_g} = \frac{1}{0.049} + \frac{1}{0.017} + \frac{1}{0.06}$$

$$C_g = 0.01 \text{ F/m}^2$$

- b) The quantum well is confined with thickness $t_w = 6\text{nm}$. Assuming infinite quantum well, the energy states of the quantized bands is given by

$$E_n = \frac{h^2 \pi^2 n^2}{2m^* t_w}$$

$$E_1 = 0.45 \text{ eV}$$

$$E_2 = 1.82 \text{ eV}$$

2. Ignoring C_c ,

$$\frac{1}{C_g} = \frac{1}{C_{ox}} + \frac{1}{C_q}$$

$$\frac{1}{C_g} = \frac{t_{ox}}{\epsilon_{ox} \epsilon_0} + \frac{\pi h^2}{q^2 m^*}$$

$$C_g = \frac{\epsilon_{ox} \epsilon_0 q^2 m^*}{t_{ox} q^2 m^* + \pi h^2 \epsilon_{ox} \epsilon_0}$$

Divide by $q^2 m^*$

$$C_g = \frac{\epsilon_{ox} \epsilon_0}{t_{ox} + \Delta t}$$

$$\Delta t = \frac{\pi h^2 \epsilon_{ox} \epsilon_0}{q^2 m^*}$$

From (1),

$$\Delta t = 11 \text{ nm}$$

3. a)

$$V_{ds,sat} = \frac{C'_{ox}}{C'_{ox} + \frac{C_q}{2}} (V_{GS} - V_T)$$

$$C'_{ox} = C_{ox} || C_c = 0.027 \text{ F/m}^2$$

$$= 0.23 \text{ V}$$

b)

$$I_{ds,sat} = \frac{qW2\sqrt{2m^*}}{3\pi^2\hbar^2} \left(\frac{qC'_{ox}}{C'_{ox} + \frac{C_q}{2}} \right)^{\frac{3}{2}} (V_{GS} - V_T)^{\frac{3}{2}}$$

$$= 1.45 \text{ mA}/\mu\text{m}$$

4. a)

$$I_{ds,sat} = \frac{qW2\sqrt{2m^*}}{3\pi^2\hbar^2} \left(\frac{qC'_{ox}}{C'_{ox} + \frac{q^2m^*}{2\pi\hbar^2}} \right)^{\frac{3}{2}} (V_{GS} - V_T)^{\frac{3}{2}}$$

- For large m^* , $(m^*)^{3/2}$ is much larger than $(m^*)^{1/2}$ and hence larger denominator causes $I_{ds,sat} \rightarrow 0$
- For small m^* , $(m^*)^{1/2}$ becomes very small and capacitance term becomes constant as m^* is small and hence $I_{ds,sat} \rightarrow 0$

b) Summarizing everything independent of m^* to be a constant K,

$$I_{ds,sat} = K \left(\frac{\sqrt{m^*}}{\left(C'_{ox} + \frac{q^2m^*}{2\pi\hbar^2} \right)^{\frac{3}{2}}} \right)$$

$$\frac{\partial I_{ds,sat}}{\partial m^*} = K \left(\frac{1}{2\sqrt{m^*} \left(C'_{ox} + \frac{q^2m^*}{2\pi\hbar^2} \right)^{\frac{3}{2}}} - \frac{3\sqrt{m^*}}{2 \left(C'_{ox} + \frac{q^2m^*}{2\pi\hbar^2} \right)^{\frac{5}{2}} \left(\frac{q^2}{2\pi\hbar^2} \right)} \right)$$

c) Taking out the common factors from both the terms in the above equation,

$$0 = \frac{1}{2} - \frac{3}{2} \frac{q^2 m^*}{2\pi h^2 \left(C'_{ox} + \frac{q^2 m^*}{2\pi h^2} \right)}$$

$$m^*_{opt} = \frac{\pi h^2 C'_{ox}}{q^2}$$

d) Using the above equation, the optimum m^* for the FET in (1) can be calculated as

$$m^* = 0.04 m_0$$

5. Since the doping level is high, one can assume a vertical contact.

Contact length $L_c = 100\text{nm}$

Contact width $W_c = 500\text{nm}$

Well thickness $t_w = 6\text{nm}$

Length between contacts $L_{gap} = 50\text{nm}$

a)

$$L_T = \sqrt{\frac{\rho_\sigma}{R_{SH}}} = \sqrt{\frac{\rho_\sigma}{\left(\frac{\rho_n}{t_w}\right)}} = \sqrt{\frac{\rho_\sigma}{\left(\frac{1/qn\mu}{t_w}\right)}}$$

$$L_T = 62 \text{ nm } (R_{SH} = 260 \Omega)$$

b)

$$R_C = R_{SH} \frac{L_T}{W_c} = 32.24 \Omega$$

c)

$$R_{access} = \frac{L_{gap}}{W_c} R_{SH} = 26 \Omega$$

d) V_{GS} gets reduced to $V_{GS} - R_S I_D$

$$\text{Source resistance } R_S = R_C + R_{access} = 58.24 \Omega$$

Assuming width of the device $W = 500\text{nm}$

Voltage drop across the source resistance $R_S I_D = 58.24 * 1.45 * 10^{-3} * 500 * 10^{-3} = 42 \text{ mV}$

Hence applied $V_{GS} - V_T$ is reduced from 0.3V to $V_{GS} - V_T - R_S I_D$ which is 0.258V

Thus the saturation current is reduced from $1.45\text{mA}/\mu\text{m}$ to $1.16\text{mA}/\mu\text{m}$.